

U.S.S.N. 10/719,550

Specification Amendments

Please replace paragraph 008 with the following re-written paragraph:

008 In the semiconductor fabrication industry, minimization of particle contamination on device structures increases in importance as the integrated circuit devices on the wafers decrease in size. With the reduced size of the devices, a contaminant having a particular size occupies a relatively larger percentage of the available space for circuit elements on the wafer as compared to wafers containing the larger devices of the past. Moreover, the presence of particles in the integrated circuits compromises the functional integrity of the devices in the finished electronic product. Currently, mini-environment based IC manufacturing facilities are equipped to control airborne particles much smaller than 1.0 micron [[m]], as surface contamination continues to be of high priority to semiconductor manufacturers. To achieve an ultraclean wafer surface, particles must be removed from the wafer, and

U.S.S.N. 10/719,550

particle-removing methods are therefore of utmost importance
in the fabrication of semiconductors.